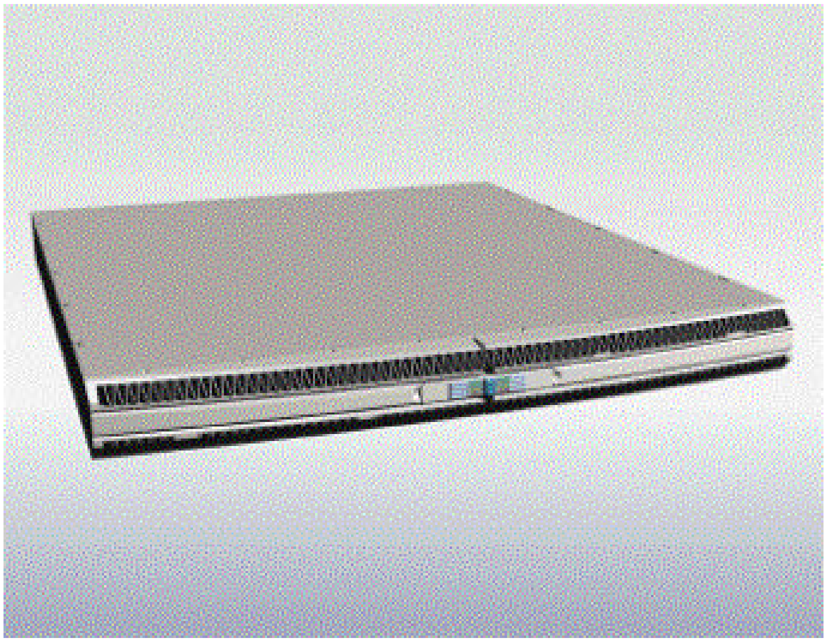
Innovative New Ultra Slice Server Solutions



- Next generation distributed server cluster
- High Density (4x), innovative thermal, shock & vibration management
- All the advantages of MIL-SPEC at a lower cost
- Modular architecture, easy configuration
- Supports heterogeneous IA (SPARC, PPC, X86)
- High speed scalable I/O grid
- Optical interface for remote I/O
- Single CPU Slice occupies 1U

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